

HC-93

Thermal Conductive Rubber Cap

LiPOLY HC-93 is a stereoscopic thermal conductive silicone rubber cap as substrate through a special production process. Due to its excellent characteristic of high thermal conductivity, insulation, shock-proof and convenient assembly, it is widely used in heat transistor refer to TO220 / TO3P, diode, triode.

■ FEATURES

- / Thermal conductivity: 2.5 W/m*K
- / Good insulator
- / High recovery
- / Easy to assemble
- / Available in a range of thicknesses

■ TYPICAL APPLICATION

- / Between CPU and heat sink
- / Between a component and heat sink
- / Notebook computers
- / Power supplies
- / High speed mass storage drives
- / Telecommunication hardware
- / 5G base station & infrastructure
- / EV electric vehicle

■ SPECIFICATIONS

/ 11.4 x 16x5.8mm / 11.4 x 21.5x5.8mm / 17.5 x 28.5x5.8mm



■ TYPICAL PROPERTIES

PROPERTY	HC-93	TEST METHOD	UNIT
Color	Gray	Visual	-
Resin base	Silicone	-	-
Thickness	0.30 / 0.45	ASTM D374	mm
Density	2.3	ASTM D792	g/cm³
Hardness	65	ASTM D2240	Shore A
Application temperature	-60~180	-	°C
ROHS & REACH	Compliant	-	-
COMPRESSION@1.0mm			
Deflection @10 psi	1	ASTM D5470 modify	%
Deflection @20 psi	2	ASTM D5470 modify	%
Deflection @30 psi	4	ASTM D5470 modify	%
Deflection @40 psi	5	ASTM D5470 modify	%
Deflection @50 psi	6	ASTM D5470 modify	%
ELECTRICAL			
Dielectric breakdown	7/8	ASTM D149	KV/mm
Surface resistivity	>1012	ASTM D257	Ohm
Volume resistivity	>10 ¹³	ASTM D257	Ohm-m
THERMAL			
Thermal Conductivity	2.5	ASTM D5470	W/m*K
Thermal impedance@10 psi	0.830	ASTM D5470	°C-in²/ W
Thermal impedance@20 psi	0.741	ASTM D5470	°C-in²/ W
Thermal impedance@30 psi	0.597	ASTM D5470	°C-in²/ W
Thermal impedance@40 psi	0.511	ASTM D5470	°C-in²/ W
Thermal impedance@50 psi	0.462	ASTM D5470	°C-in²/ W

Thermal Resistance vs. Pressure

